

描述 / Descriptions

3.0A 表面贴装玻璃钝化整流桥，薄型 UMSB 封装。

3.0A Surface Mount Glass Passivated Bridge Rectifier, UMSB thin package.

特征 / Features

玻璃钝化芯片，浪涌电流大，反向电压：100V~1000V，正向电流：3.0A，适用表面贴装。无卤产品。

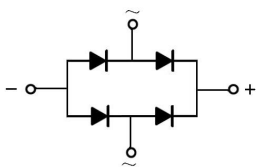
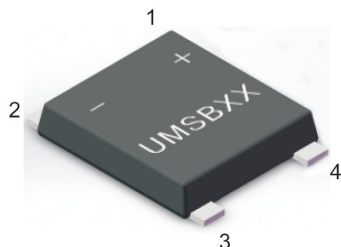
Glass Passivated Chip Junction, High Surge Current Capability, Reverse Voltage :100 to 1000V,

Forward Current: 3.0A, Designed for Surface Mount Application. HF product.

用途 / Applications

一般用途。

General purpose.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN	DESCRIPTION
1	Output Anode (+)
2	Output Cathode (-)
3	Input Pin (~)
4	Input Pin (~)

印章代码 / Marking

见印章说明。See Marking Instructions.


极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		MSB30B	MSB30D	MSB30G	MSB30J	MSB30K	MSB30M	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current	I_o	3.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	80						A
Typical Junction Capacitance (Note1)	C_i	40						pF
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150						°C

Note:

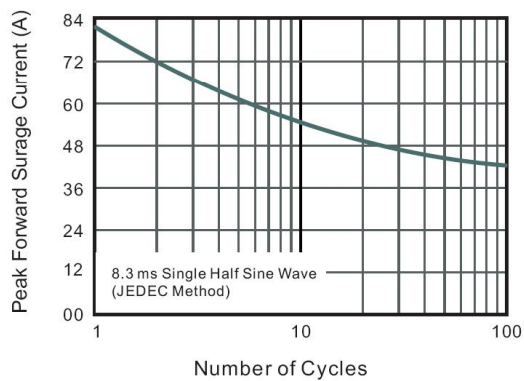
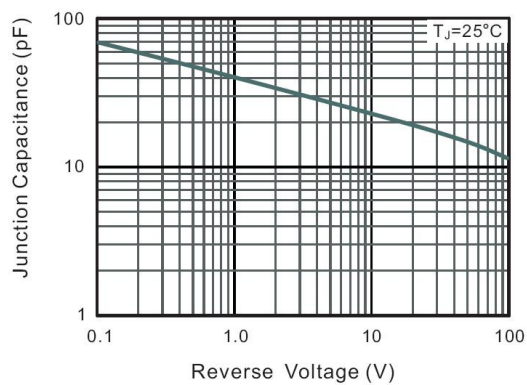
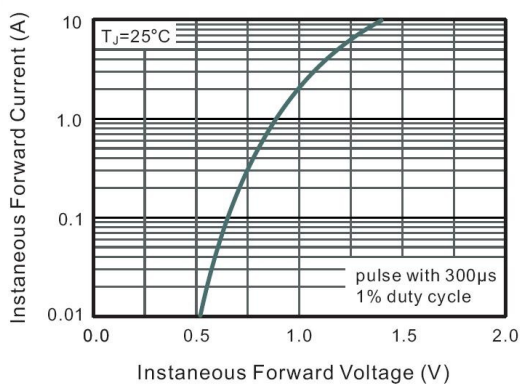
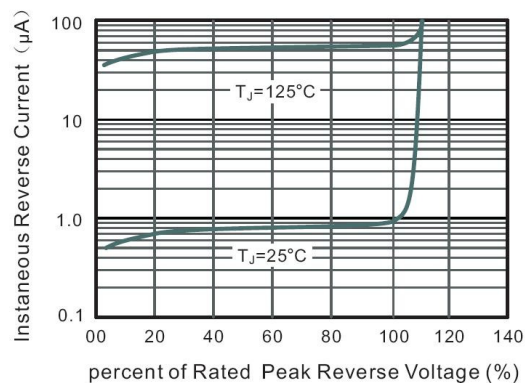
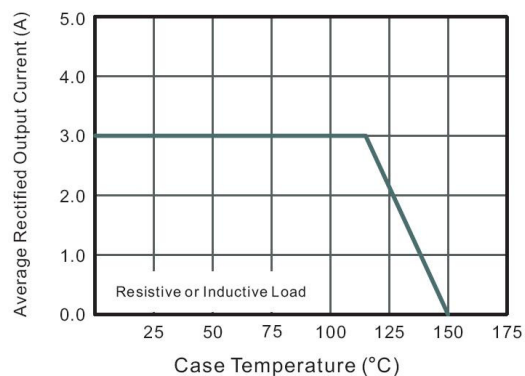
1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. P.C.B. mounted with 4x1.5" x1.5" (3.81x3.81cm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Forward Voltage per element	V_F	$I_F=3.0A$	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25^{\circ}C$	5.0	μA
		$T_a=125^{\circ}C$	100	

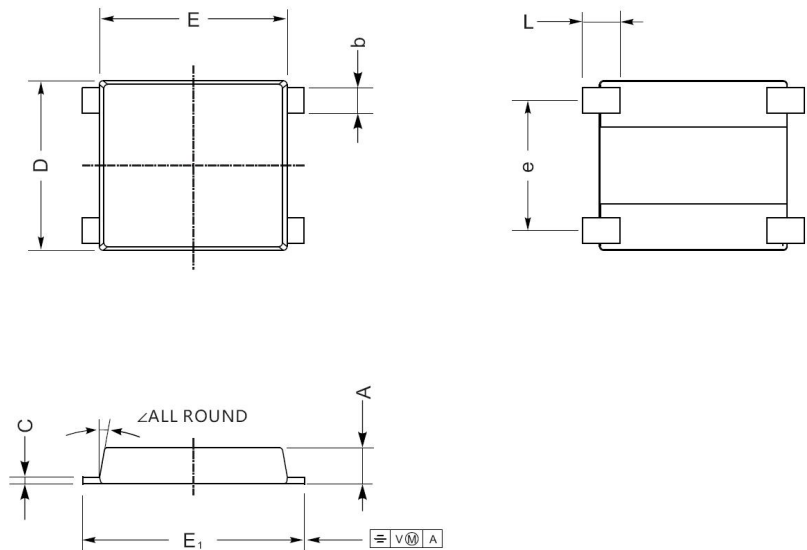


电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

UMSB



UMSB mechanical data

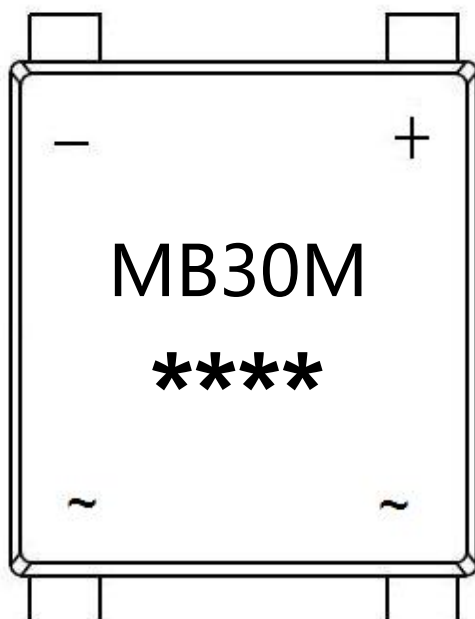
UNIT		A	C	D	E	E ₁	L	e	b	∠
mm	max	1.5	0.29	7.0	7.6	8.9	1.6	5.3	1.15	10°
	min	1.3	0.17	6.2	7.1	8.4	1.0	4.9	0.95	
mil	max	59	12	276	299	350	55	209	45	
	min	51	7	244	280	331	31.5	193	37	



Marking

Type number	Marking code
MSB30B	MB30B
MSB30D	MB30D
MSB30G	MB30G
MSB30J	MB30J
MSB30K	MB30K
MSB30M	MB30M

印章说明 / Marking Instructions



说明

MB30M : 为型号代码

**** : 为生产批号追溯码，第 1 个*为年月代码，后面 3 个*为当月小批号代码

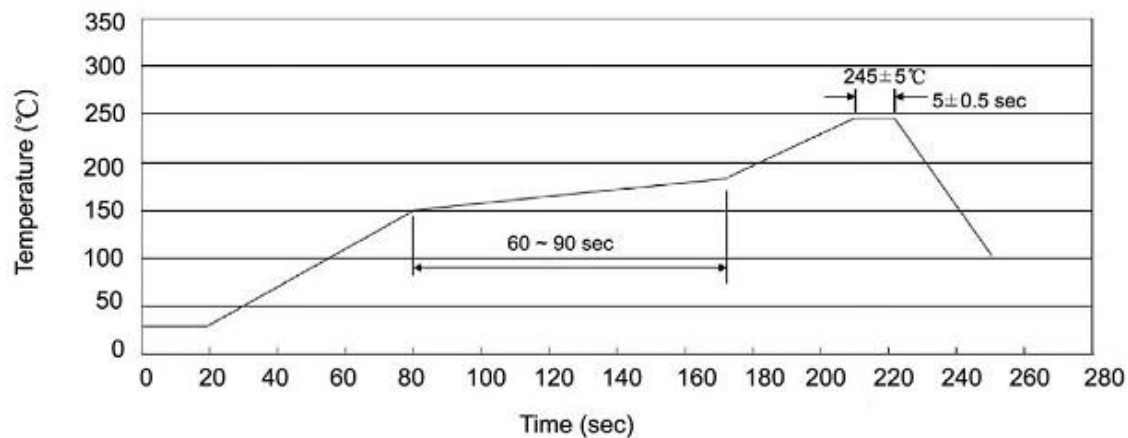
Note:

MB30M : Product Type Code

**** : Lot No. Code , The 1st * means:YM Code , The last 3 * means:little Lot
No Code



回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
UMSB	3000	2	6000	5	30000	13 "×16	337 × 337 × 49	345 × 345 × 280

使用说明 / Notices